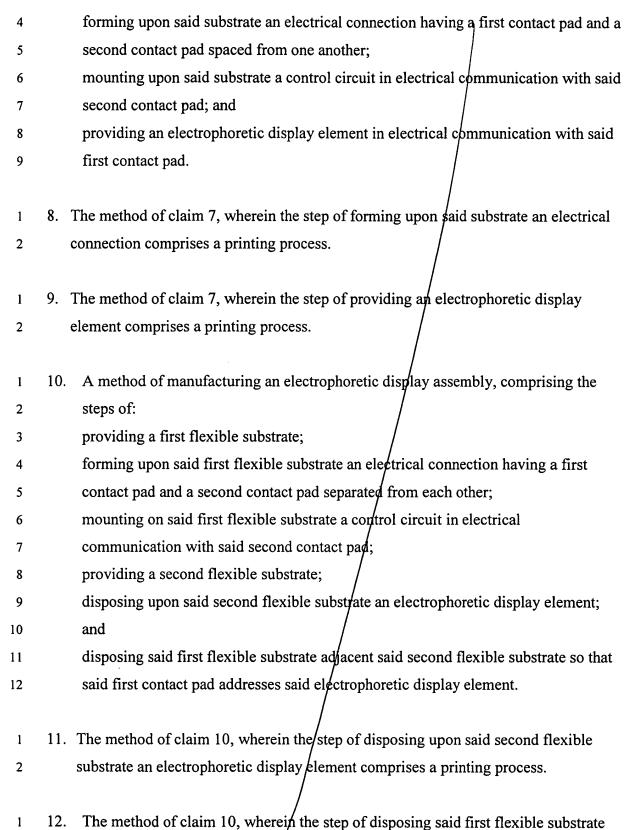
CLAIMS

≤ 1	\int_{0}^{∞}	1	1.	A mounted electrophoretic display assembly, comprising:
		2/		a flexible substrate;
al		3		an electrical connection formed on said flexible substrate and having first and
/		4		second contact pads spaced from one another;
,		5		an electrophoretic display element in electrical communication with said first
	The state of the s	6		contact pad; and
		7		a control circuit mounted on said flexible substrate and in electrical communication
		8		with said second contact pad.
		1	2.	The display assembly of claim 1, wherein said control circuit is connected to said
		2		second contact pad with a curable, electrically conductive thermoset.
		1	3.	The display assembly of claim 1, wherein said control circuit is connected to said
		2		second contact pad with an electrically conductive ink.
		1	4.	The display assembly of claim 1, wherein said control circuit is connected to said
		2		second contact pad with an electrically conductive paint.
		1	5.	The display assembly of claim 1, wherein said control circuit is connected to said
		2		second contact pad by being removably mounted in a control circuit carrier that is in
		3		electrical communication with said second contact pad.
		1	6.	The display assembly of claim 1 wherein said control circuit comprises an
		2		electrophoretic display driver chip.
		1	7/.	A method of manufacturing an electrophoretic display assembly, comprising the steps
		2	(of:

providing a flexible substrate;

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adjacent said second flexible substrate further comprises a laminating process.